

RLDRAM 3 Errata

MT44K64M18 – 4 Meg x 18 x 16 Banks

MT44K32M36 – 2 Meg x 36 x 16 Banks

1Gb (30nm SDP): Die Rev. A

- All specifications defined in Micron's standard 1.125Gb RLD RAM 3 data sheet are applicable except post package repair (PPR).
- The PPR mode has not yet been enabled. No repairs will be done if this feature is used.

Options¹

Options ¹	Marking
• Clock cycle and ^t RC timing	
– 0.83ns and ^t RC (MIN) = 6.67ns (RL3-2400)	-083F
– 0.83ns and ^t RC (MIN) = 7.5ns (RL3-2400)	-083E
– 0.93ns and ^t RC (MIN) = 7.5ns (RL3-2133)	-093F
– 0.93ns and ^t RC (MIN) = 8ns (RL3-2133)	-093E
– 1.07ns and ^t RC (MIN) = 8ns (RL3-1866)	-107E
• Configuration	
– 64 Meg x 18	64M18
– 32 Meg x 36	32M36
• Operating temperature	
– Commercial (T _C = 0° to +95°C)	None
– Industrial (T _C = -40°C to +95°C)	IT
• Package	
– 168-ball BGA (Pb-free)	RB
• Revision	:A

Note: 1. Not all options listed can be combined to define an offered product. Use the part catalog search on www.micron.com for available offerings.



1.125Gb x18, x36 RLDRAM 3 Errata 1Gb (30nm SDP): Die Rev. A

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This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein.
Although considered final, these specifications are subject to change, as further product development and data characterization some-
times occur.